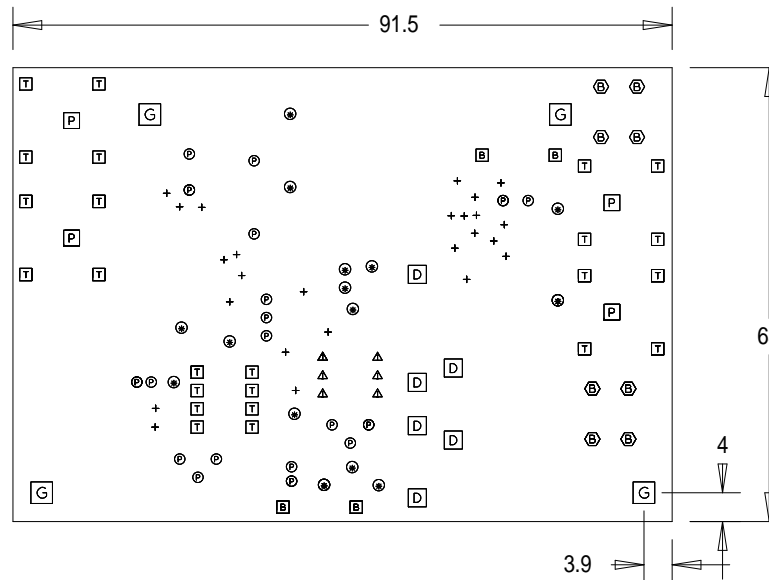



SPEC:

COMPLIANT RoHS DIRECTIVE 2011/65/UE

MATERIAL	FR4 IMPROVED (low CTE)		
BOARD THICKNESS		1.6mm /63mils	
STACKUP	DF /2LAYERS		
MINIMAL GAP		210um /8.0mils	
MINIMAL SLIVER		210um /8.0mils	
COPPER THICKNESS		35um(1oz)at START	
FINISH THICKNESS	CHEMICAL NiAu		
SOLDER MASK		GREEN TOP & BOT	
SILKSCREEN	WHITE TOP		
ALL BOARD ELECTRICALLY TESTED			
MANUFACTURE 'S LOGO & DATECODE MARKED ON BOTTOM SOLDERMASK			



DRILL CHART: TOP to BOTTOM					
ALL UNITS ARE IN MILLIMETERS					
FIGURE	SIZE		TOLERANCE	PLATED	QTY
+	0.5	VIA	+0.0/-0.0	PLATED	25
⊙	0.8		+0.1/-0.05	PLATED	19
△	0.9		+0.1/-0.05	PLATED	6
⊙	1.0		+0.1/-0.05	PLATED	15
⊙	1.1		+0.1/-0.05	PLATED	4
⊙	1.4		+0.1/-0.05	PLATED	24
⊙	2.0		+0.1/-0.05	PLATED	8
P	2.2		+0.1/-0.05	PLATED	4
D	2.25		+0.05/-0.05	PLATED	6
G	3.0		+0.1/-0.1	NON-PLATED	4

1.0		w34/2018	
indice	Description		Date
Contrôle par :		Autorise par:	
 ON semiconductor		Definition CUT DRILL DRAWING PLAN PRECAGE DETOURAGE	
		Subc. DYPE TECH	Dessine: e B
Board: CM BUCK UC384x EVB-A-TLS		Echelle: 1/1	Pages: 1/3
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